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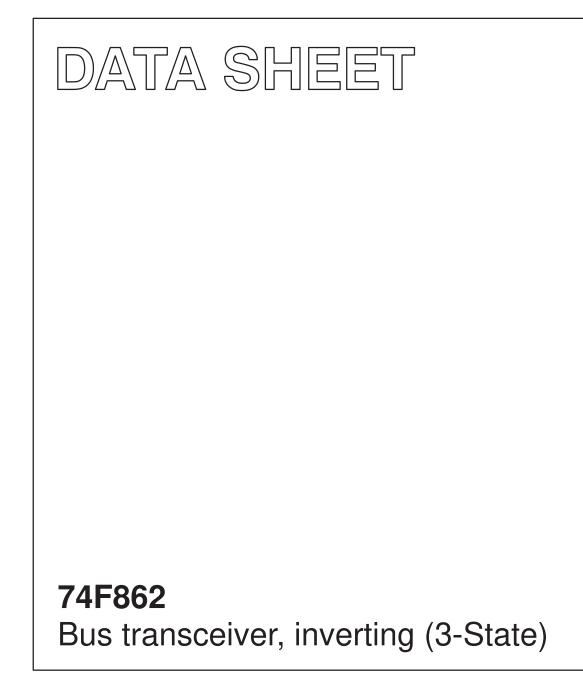


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INTEGRATED CIRCUITS



Product data Replaces data sheet 74F862, 74F863 of 2000 Mar 24 2004 Jan 23



74F862

FEATURES

- Provide high performance bus interface buffering for wide data/address paths or buses carrying parity
- \bullet High impedance NPN base inputs for reduced loading (20 μA in HIGH and LOW states)
- I_{IL} is 20 μ A for minimum bus loading
- Buffered control inputs for light loading, or increased fan-in as required with MOS microprocessors
- · Positive and negative over-shoots are clamped to ground
- 3-State outputs glitch free during power-up and power-down
- Slim dual In-line (DIP) 300 mil package
- Broadside pinout
- Outputs sink 64 mA

ORDERING INFORMATION

COMMERCIAL RANGE: $V_{CC} = 5 V \pm 10\%$; $T_{amb} = 0 \circ C \text{ to } +70 \circ C$

DESCRIPTION

The 74F862 bus transceiver provides a high performance inverting bus interface for wide data/address paths of buses carrying parity.

ТҮРЕ	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F862	6.0 ns	150 mA

Type number	Package	Package				
	Name	ame Description				
N74F862N	DIP24	plastic dual in-line package; 24 leads (300 mil)	SOT222-1			
N74F862D (see Note 1)	SO24	plastic small outline package; 24 leads; body width 7.5 mm	SOT137-1			

NOTE:

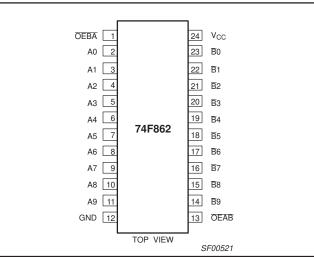
1. Thermal mounting techniques are recommended. See SMD Process Applications for a discussion of thermal considerations for surface mounted devices.

INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

PINS	DESCRIPTION	74F(U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
A0 – A9	Data transmit inputs	1.0/0.033	20 µA / 20 µA
<u>B</u> 0 – <u>B</u> 9	Data receive inputs	1.0/0.033	20 μΑ / 20 μΑ
OEBA	Transmit output enable input	1.0/0.033	20 μA / 20 μA
OEAB	Receive output enable input	1.0/0.033	20 μA / 20 μA

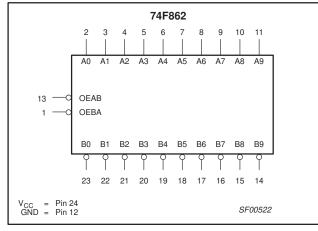
NOTE: One (1.0) FAST Unit Load is defined as: 20 µA in the HiGH state and 0.6 mA in the LOW state.

PIN CONFIGURATION

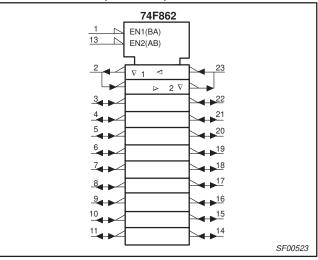


74F862

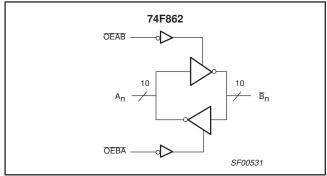
LOGIC SYMBOL



LOGIC SYMBOL (IEEE/IEC)



LOGIC DIAGRAM



FUNCTION TABLE

INP	UTS	OPERATING MODES
OEAB	OEBA	OPERATING MODES
L	Н	A data to B bus, inverted
Н	L	B bus to A data, inverted
Н	Н	Z

H = HIGH voltage level L = LOW voltage level Z = High impedance "off" state

74F862

ABSOLUTE MAXIMUM RATINGS

Operation beyond the limits set forth in this table may impair the useful life of the device. Unless otherwise noted, these limits are over the operating free-air temperature range.

SYMBOL	PARAMETER	RATING	UNIT
V _{CC}	Supply voltage	-0.5 to +7.0	V
V _{IN}	Input voltage	-0.5 to +7.0	V
I _{IN}	Input current	-30 to +5	mA
V _{OUT}	Voltage applied to output in HIGH output state	-0.5 to +5.5	V
I _{OUT}	Current applied to output in LOW output state	128	mA
T _{amb}	Operating free-air temperature range	0 to +70	°C
T _{stg}	Storage temperature	-65 to +150	°C

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER		UNIT		
STMBOL		MIN	NOM	МАХ	UNIT
V _{CC}	Supply voltage	4.5	5.0	5.5	V
V _{IH}	HIGH-level input voltage	2.0	-	-	V
V _{IL}	LOW-level input voltage	-	-	0.8	V
I _{IK}	Input clamp current	-	-	-18	mA
I _{OH}	HIGH-level output current	-	-	-24	mA
I _{OL}	LOW-level output current	-	-	64	mA
T _{amb}	Operating free-air temperature range	0	-	70	°C

DC ELECTRICAL CHARACTERISTICS

Over recommended operating free-air temperature range unless otherwise noted.

0////	DL PARAMETER			TEST CONDITIONS ¹			LIMITS		
SYMBOL	PARAMETER	1	TEST CONDITIONS'			MIN	TYP ²	MAX	UNIT
			± 10% V _{CC}	2.4	-	-	V		
V _{OH}			V _{IL} = MAX, V _{IH} = MIN	I _{OH} = -1 mA	\pm 5% V _{CC}	2.4	3.3	-	V
	HIGH-level output voltage		$V_{CC} = MIN,$ $V_{IL} = MAX,$	I _{OH} =24 mA	\pm 10% V _{CC}	2.0	-	-	V
					\pm 5% V _{CC}	2.0	-	-	V
M			$V_{CC} = MIN,$	I _{OL} = 48 mA	\pm 10% V _{CC}	-	0.38	0.55	V
V _{OL}	LOW-level output voltage		V _{IL} = MAX, V _{IH} = MIN	I _{OL} = 64 mA	\pm 5% V _{CC}	-	0.42	0.55	V
V _{IK}	Input clamp voltage		$V_{CC} = MIN, I_I = I_{IK}$			-	-0.73	-1.2	V
	Input current at maximum	OEAB, OEBA	$V_{CC} = 0.0 \text{ V}, \text{ V}_{I} = 7.0 \text{ V}$		-	-	100	μA	
łı	input voltage	A_n, \overline{B}_n	$V_{CC} = 5.5 \text{ V}, \text{ V}_{I} = 5.5 \text{ V}$			-	-	1	mA
I _{IH}	HIGH-level input current		$V_{CC} = MAX, V_I = 2.7 V$		-	-	20	μA	
۱ _{IL}	LOW-level input current		$V_{CC} = MAX, V_I = 0.5 V$		-	-	-20	μA	
I _{IH} + I _{OZH}	Off-state output current HIGH-level voltage applied	A 5	$V_{CC} = MAX, V_O = 2.7 V$		-	-	70	μA	
I _{IL} + I _{OZL}	Off-state output current LOW-level voltage applied	A _n , D _n	A_n, \overline{B}_n $V_{CC} = MAX, V_O = 0.5 V$			-	-	-70	μA
I _{OS}	Short-circuit output current ³	-	V _{CC} = MAX		-100	-	-225	mA	
-		ICCH				-	90	130	mA
ICC	Supply current total	I _{CCL}	V _{CC} = MAX			-	120	170	mA
		I _{CCZ}				-	130	160	mA

NOTES:

1. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.

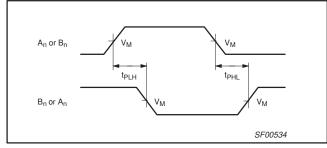
2. All typical values are at $V_{CC} = 5 \text{ V}$, $T_{amb} = 25 \text{ °C}$. 3. Not more than one output should be shorted at a time. For testing I_{OS} , the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a HIGH output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

AC ELECTRICAL CHARACTERISTICS

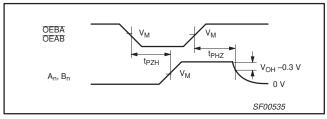
					LIMIT	S		
SYMBOL	PARAMETER	TEST CONDITION		_{mb} = +25 V _{CC} = 5 V 0 pF; R _L =		T _{amb} = 0 °C V _{CC} = 5 C _L = 50 pF;		UNIT
			MIN	ТҮР	MAX	MIN	MAX	
t _{PLH} t _{PHL}	Propagation delay A_n or \overline{B}_n	Waveform 1	4.0 1.5	6.0 3.5	9.0 6.5	3.0 1.5	10.0 7.0	ns
t _{PLH} t _{PHL}	Propagation delay \overline{B}_n or A_n	Waveform 1	4.0 1.5	6.0 3.5	9.0 6.5	3.5 1.5	10.0 7.0	ns
t _{PZH} t _{PZL}	Output Enable time HIGH or LOW level OEBA to A _n	Waveform 2 Waveform 3	6.5 6.0	8.5 7.5	12.0 12.0	5.5 5.0	13.5 14.0	ns
t _{PZH} t _{PZL}	Output Enable time HIGH or LOW level \overline{OEAB} to \overline{B}_n	Waveform 2 Waveform 3	6.5 6.0	8.5 7.5	12.0 12.0	5.5 5.0	13.5 14.0	ns
t _{PHZ} t _{PLZ}	Output Disable time HIGH or LOW level OEBA to A _n	Waveform 2 Waveform 3	3.0 2.5	5.0 4.0	8.5 8.5	2.5 2.0	9.5 9.0	ns
t _{PHZ} t _{PLZ}	Output Disable time HIGH or LOW level $\overline{\text{OEAB}}$ to $\overline{\text{B}}_{\text{n}}$	Waveform 2 Waveform 3	3.0 2.5	5.0 4.0	8.5 8.5	2.5 2.0	9.5 9.0	ns

AC WAVEFORMS

For all waveforms, $V_M = 1.5 V$.

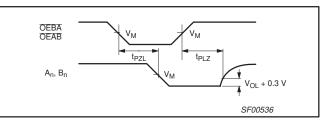


Waveform 1. Propagation delay for inverting output

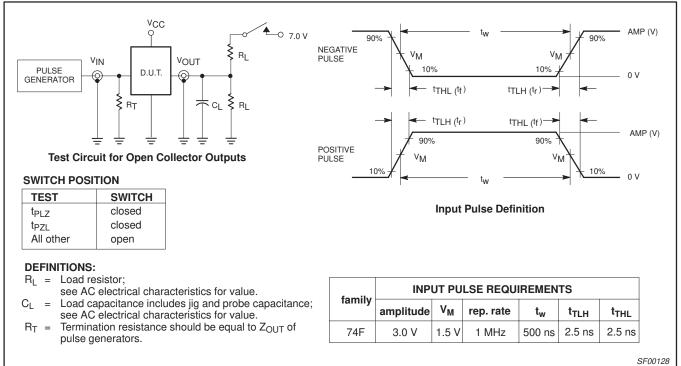


Waveform 2. 3-State Output Enable time to HIGH level and Output Disable time from HIGH level

TEST CIRCUITS AND WAVEFORMS



Waveform 3. 3-State Output Enable time to LOW level and Output Disable time from LOW level



74F862

inches

Note

0.185

OUTLINE

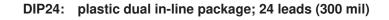
VERSION

SOT222-1

0.015

0.155

IEC



0.064

0.045

1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

0.022

0.017

JEDEC

MS-001

0.014

0.010

REFERENCES

1.256

1.240

0.265

0.246

0.1

0.3

0.138

0.120

0.395

0.300

0.01

ISSUE DATE

-99-12-27-

03-03-12

0.081

0.32

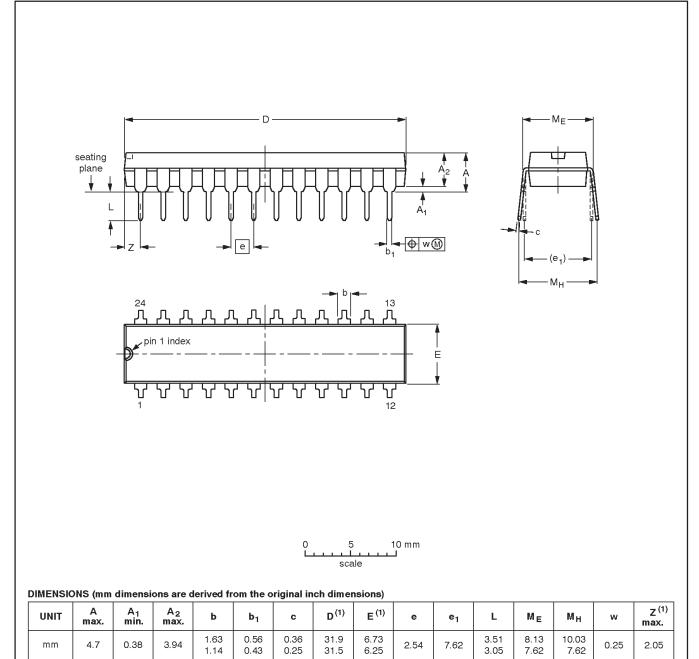
0.30

EUROPEAN

PROJECTION

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74F862

SOT222-1

JEITA



SO24: plastic small outline package; 24 leads; body width 7.5 mm SOT137-1 D А Х = v 🕅 A Ду 13 Q A٥ Å (A A pin 1 index 12 detail X J**↓** ₽_₽₽₩₩ e 10 mm 0 5 scale DIMENSIONS (inch dimensions are derived from the original mm dimensions) Α E⁽¹⁾ D ⁽¹⁾ z⁽¹⁾ UNIT A_1 с ${\rm H}_{\rm E}$ L Q v θ A_2 A_3 bp е Lp w У max. 2.45 0.32 10.65 0.49 15.6 7.6 0.9 0.3 1.1 1.1 mm 2.65 0.25 1.27 0.25 0.25 0.1 1.4 0.1 2.25 0.36 0.23 15.2 7.4 10.00 0.4 1.0 0.4 8° 00 0.035 0.012 0.096 0.019 0.013 0.61 0.30 0.419 0.043 0.043 inches 0.1 0.01 0.05 0.055 0.01 0.01 0.004 0.004 0.089 0.014 0.009 0.60 0.29 0.394 0.016 0.039 0.016 Note 1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE	REFERENCES				EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT137-1	075E05	MS-013				-99-12-27 03-02-19

Rev	Date	Description
_5	20040123	Product data (9397 750 12749). ECN 853-0881 A15378 of 22 January 2004. Replaces Product specification 74F862_74F863_4 dated 2000 Mar 24 (9397 750 06999).
		Modifications:
		• Delete all references to 74F863 (product discontinued).
		 "Input and output loading and fan-out table" on page 2; for Pins A0 – A9 and B0 – B9: – change 74F(U.L.) HIGH/LOW from "3.5/0.117" to "1.0/0.033" – change Load value HIGH/LOW from "70 μA / 70 μA" to "20 μA / 20 μA"
		 "DC electrical characteristics" table on page 5; V_{OL} test condition, at ± 10% V_{CC}: change "I_{OL} = -48 mA" to "I_{OL} = 48 mA"
_4	20000324	Product specification (9397 750 06999). ECN 853-0881 23378 of 24 March 2000. Supersedes data of 1999 Jan 08.

74F862

74F862

Product data

Data sheet status

Level	Data sheet status ^[1]	Product status ^{[2] [3]}	Definitions
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

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[2] The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.

[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

Definitions

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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